

Absolute Maximum Ratings

(Ta=25°C, unless otherwise specified)

Characteristic	Symbol	Value	Unit
Drain-Gate Voltage(RGS=1MΩ)	VDGR	650	V
Gate-Source(GND) Voltage	VGS	±30	V
Drain Current Pulsed ⁽¹⁾	IDM	48	ADC
Continuous Drain Current (Tc = 25°C)	ID	12	ADC
Continuous Drain Current (Tc = 100°C)	ID	8.4	ADC
Single Pulsed Avalanche Current ⁽³⁾ (Energy ⁽²⁾)	IAS(EAS)	30(950)	A(mJ)
Maximum Supply Voltage	VCC,MAX	35	V
Input Voltage Range	VFB	-0.3 to VCC	V
	VSS	-0.3 to 10	V
Total Power Dissipation	PD (Watt H/S)	240	W
	Darting	1.92	W/°C
Operating Junction Temperature.	TJ	+150	°C
Operating Ambient Temperature.	TA	-25 to +85	°C
Storage Temperature Range.	TSTG	-55 to +150	°C

Note:

1. Repetitive rating: pulse width limited by maximum junction temperature
2. L = 10mH, starting Tj = 25°C
3. L = 13uH, starting Tj = 25°C

Electrical Characteristics (SFET Part)

(Ta = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BVDSS	VGS = 0V, ID = 50μA	650	-	-	V
Zero Gate Voltage Drain Current	IDSS	VDS=Max, Rating, VGS = 0V	-	-	200	μA
		VDS= 0.8Max, Rating, VGS = 0V, TC = 125°C	-	-	300	μA
Static Drain-Source on Resistance ⁽¹⁾	RDS(on)	VGS = 10V, ID = 4.5A	-	0.7	0.9	Ω
Forward Transconductance ⁽²⁾	gfs	VDS = 50V, ID = 4.5A	-	-	-	S
Input Capacitance	Ciss	VGS = 0V, VDS = 25V, f = 1MHz	-	1820	-	pF
Output Capacitance	Coss		-	185	-	
Reverse Transfer Capacitance	Crss		-	32	-	
Turn on Delay Time	td(on)	VDD = 0.5BVDSS, ID = 12.0A (MOSFET switching time are essentially independent of operating temperature)	-	38	-	nS
Rise Time	tr		-	120	-	
Turn Off Delay Time	td(off)		-	200	-	
Fall Time	tf		-	100	-	
Total Gate Charge (Gate-Source+Gate-Drain)	Qg	VGS = 10V, ID = 12.0A, VDS = 0.5BVDSS(MOSFET Switching time are Essentially independent of Operating temperature)	-	60	-	nC
Gate-Source Charge	Qgs		-	10	-	
Gate-Drain (Miller) Charge	Qgd		-	30	-	

Note:

1. Pulse test: pulse width ≤ 300us, duty 2%

$$2. S = \frac{1}{R}$$

Electrical Characteristics (Control Part) (Continued)

(VCC=16V, Tamb = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
UVLO SECTION						
Start Threshold Voltage	VSTART	VFB=GND	14	15	16	V
Stop Threshold Voltage	VSTOP	VFB=GND	8	9	10	V
OSCILLATOR SECTION						
Initial Frequency	FOSC	-	22	25	28	kHz
Voltage Stability	FSTABLE	12V ≤ VCC ≤ 23V	0	1	3	%
Temperature Stability (Note2)	ΔFOSC	-25°C ≤ Ta ≤ 85°C	0	±5	±10	%
Maximum Duty Cycle	DMAX	-	92	95	98	%
Minimum Duty Cycle	DMIN	-	-	-	0	%
FEEDBACK SECTION						
Feedback Source Current	IFB	VFB=GND	0.7	0.9	1.1	mA
Shutdown Feedback Voltage	VSD	VFB ≥ 6.9V	6.9	7.5	8.1	V
Shutdown Delay Current	IDELAY	VFB=5V	1.6	2.0	2.4	μA
SYNC. & SOFTSTART SECTION						
Softstart Voltage	VSS	VFB=2V	4.7	5.0	5.3	V
Softstart Current	ISS	VSS=0V	0.8	1.0	1.2	mA
Sync High Threshold Voltage(Note3)	VSYNCH	VCC=16V , VFB=5V	-	7.2	-	V
Sync Low Threshold Voltage(Note3)	VSYNCL	VCC=16V , VFB=5V	-	5.8	-	V
BURST MODE SECTION						
Burst Mode Low Threshold Voltage	VBURL	VFB=0V	10.4	11.0	11.6	V
Burst Mode High Threshold Voltage	VBURH	VFB=0V	11.4	12.0	12.6	V
Burst Mode Enable Feedback Voltage	VBEN	VCC=10.5V	0.7	1.0	1.3	V
Burst Mode Peak Current Limit(Note4)	IBURPK	-	0.45	0.6	0.75	A
Burst Mode Frequency	FBUR	VCC=10.5V , VFB=0V	40	50	60	kHz
CURRENT LIMIT(SELF-PROTECTION)SECTION						
Peak Current Limit (Note4)	I _{OVER}	-	7.04	8.0	8.96	A
PROTECTION SECTION						
Over Voltage Protection	VOVP	VCC ≥ 27V	27	30	33	V
Over Current Latch voltage(Note3)	VOCL	-	0.9	1.0	1.1	V
Thermal Shutdown Temperature(Note2)	TSD	-	140	160	-	°C
TOTAL DEVICE SECTION						
Start-Up Current	ISTART	VFB = GND, VCC = 14V	-	0.1	0.17	mA
Operating Supply Current(Note1)	IOP	VFB = GND, VCC = 16V	-	10	15	mA
	IOP(MIN)	VFB = GND, VCC = 12V				
	IOP(MAX)	VFB = GND, VCC = 30V				

Notes:

1. These parameters are the Current Flowing in the Control IC.
2. These parameters, although guaranteed, are not 100% tested in production
3. These parameters, although guaranteed, are tested in EDS(wafer test) process
4. These parameters are indicated Inductor Current.

Typical Performance Characteristics

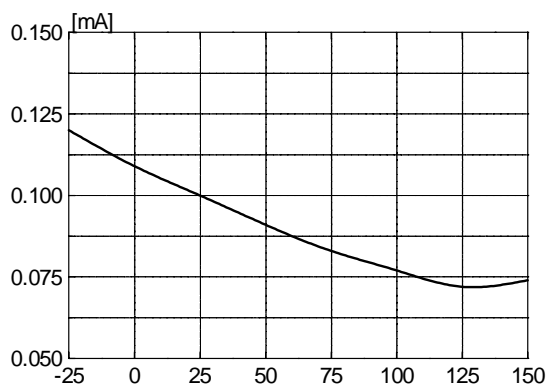


Figure 1. Start Up Current vs. Temp.

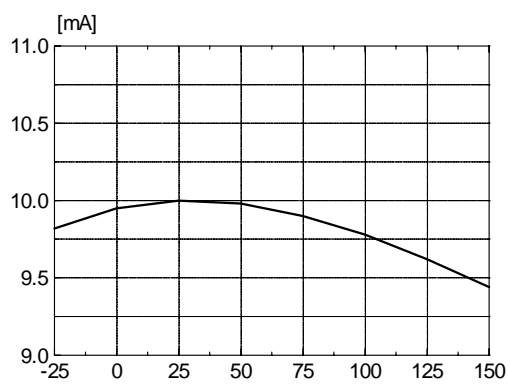


Figure 2. Operating Current vs. Temp.

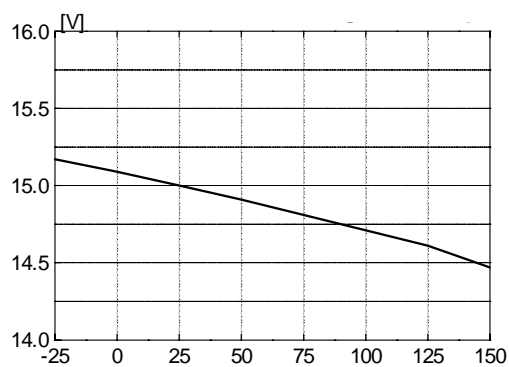


Figure 3. Start Threshold Voltage vs. Temp.

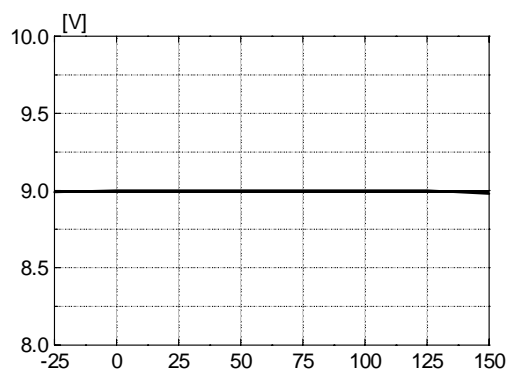


Figure 4. Stop Threshold Voltage vs. Temp.

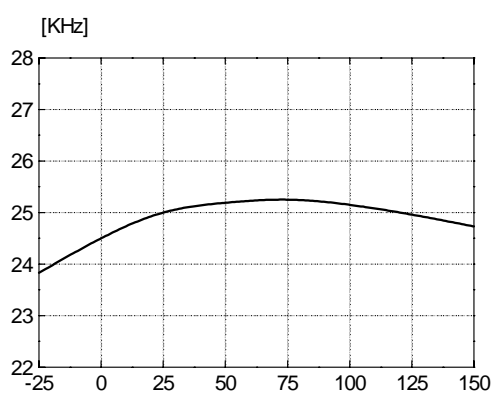


Figure 5. Initial Frequency vs. Temp.

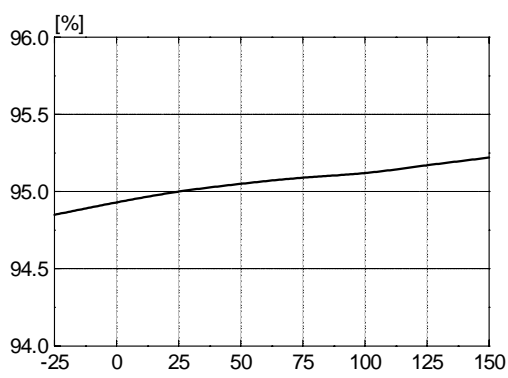


Figure 6. Maximum Duty vs. Temp.

Typical Performance Characteristics (Continued)

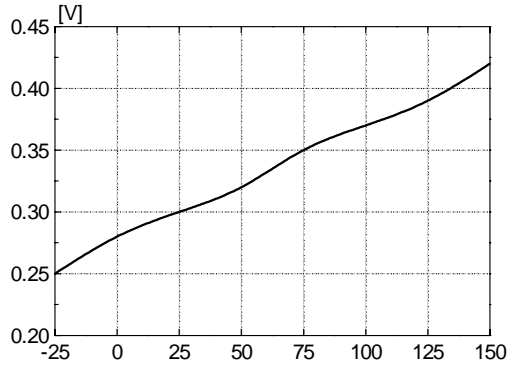


Figure 7. Feedback Offset Voltage vs. Temp.

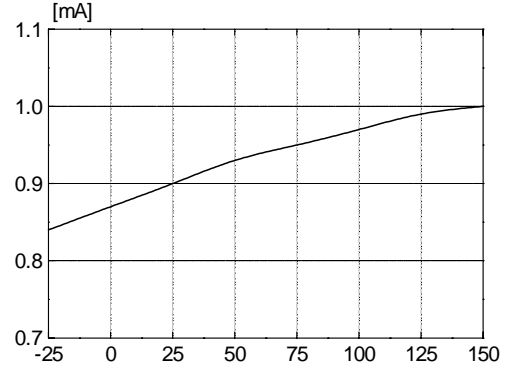


Figure 8. Feedback Source Current vs. Temp.

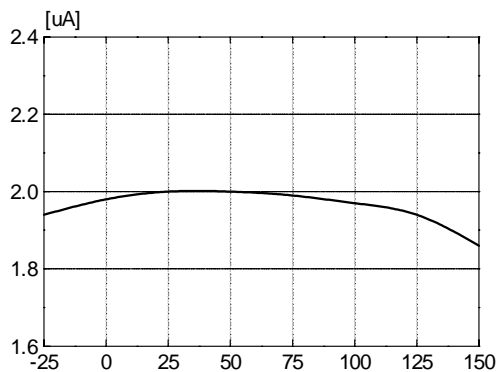


Figure 9. Shutdown Delay Current vs. Temp.

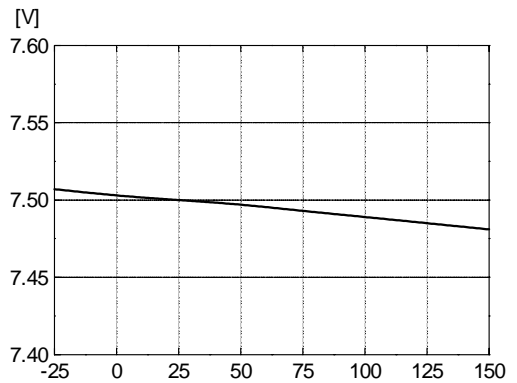


Figure 10. Shutdown Feedback Voltage vs. Temp.

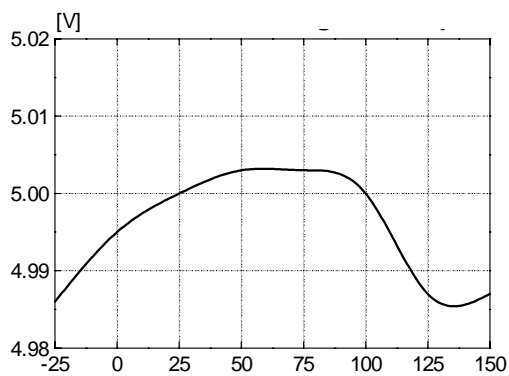


Figure 11. Softstart Voltage vs. Temp.

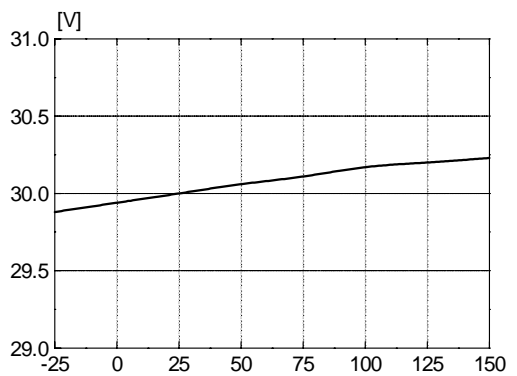


Figure 12. Over Voltage Protection vs. Temp.

Typical Performance Characteristics (Continued)

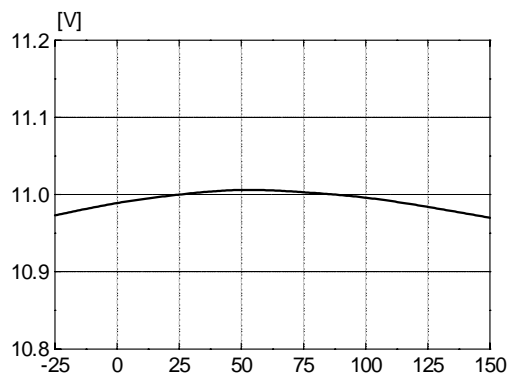


Figure 13. Burst Mode Low Voltage vs. Temp.

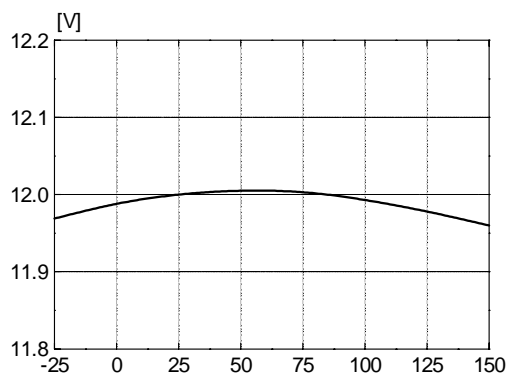


Figure 14. Burst Mode High Voltage vs. Temp.

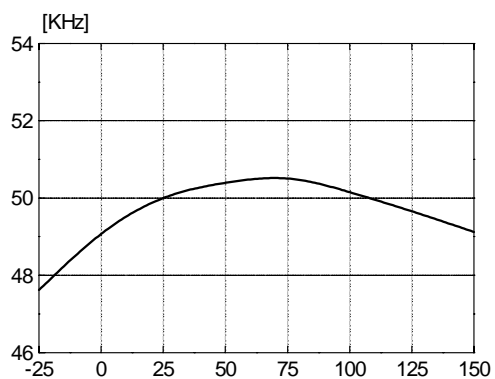


Figure 15. Burst Mode Frequency vs. Temp.

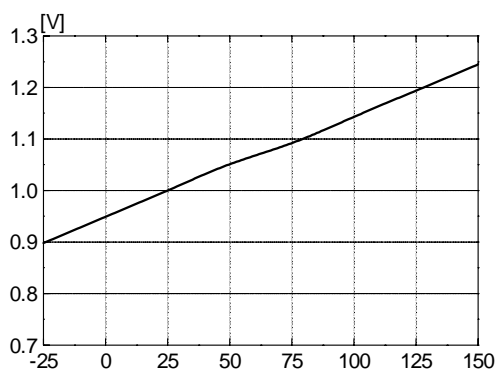


Figure 16. Burst Mode Enable Voltage vs. Temp.

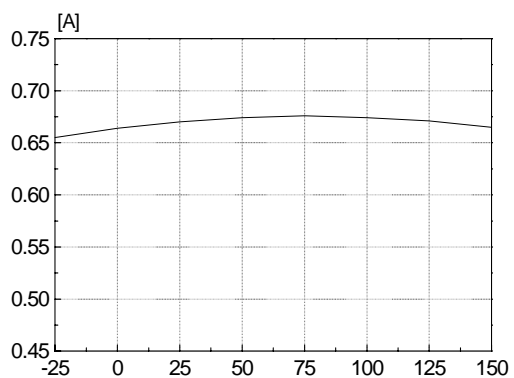


Figure 17. Burst Mode Peak Current vs. Temp.

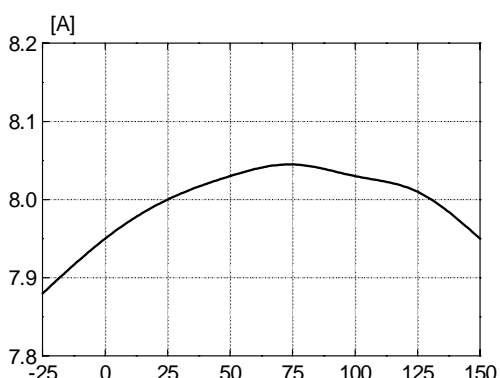


Figure 18. Peak Current Limit vs. Temp.

Ordering Information

Product Number	Package	Marking Code	BVdss	Rds(on)
FS6S1265RETU	TO-3P-5L	6S1265R E	650V	0.7Ω
FS6S1265REYDTU	TO-3P-5L(Forming)			

TU : Non Forming Type

YDTU : Forming Type

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